

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-41. (Canceled)

42. (Original) A semiconductor device, comprising:

a plurality of stacked semiconductor chips having substantially the same structure, each of the semiconductor chips including a semiconductor substrate, terminals of A groups (A is an integer equal to or larger than 2 (two)) formed on the semiconductor substrate, each of the groups including a plurality of terminals and an integrated circuit formed on the semiconductor substrate,

the plurality of terminals in each of the groups being arranged in accordance with a predetermined basic terminal arrangement,

each of the groups being disposed at each of positions that are defined by rotating one of the positions around a point;

each of the groups including a group of contact/non-contact terminals at a same positions of the group of the basic terminal arrangement, the group of contact/non-contact terminals including a contact terminal that is electrically coupled to a same-function circuit and non-contact terminals that are electrically isolated from the same-function circuit;

the contact terminal being disposed at a different position of the basic terminal arrangement for each of the groups; and

the plurality of semiconductor chips being disposed so that the point of each of the semiconductor chips coincides with each other and each of the semiconductor chips being rotated around the point by each of angles different from each other, and thereby the groups whose positions of the contact terminal in the basic terminal arrangement are different from each other overlap, the terminals, which overlap, being electrically coupled to each other.

43. (Original) A semiconductor device, comprising:
- a plurality of stacked semiconductor chips having substantially the same structure, each of the semiconductor chips including a semiconductor substrate, terminals of A groups (A is an integer equal to or larger than 2 (two)) formed on the semiconductor substrate, each of the groups including a plurality of terminals and an integrated circuit formed on the semiconductor substrate,
- the plurality of terminals in each of the groups being arranged in accordance with predetermined basic terminal arrangement,
- each of the groups being disposed at each of positions that are defined by rotating one of the positions around a point;
- the integrated circuit includes a converter, the converter including B conversion input parts (B is an integer equal to or larger than 2 (two)) and having the function of selecting at least one signal among a group of predetermined output signals of the same kind in response to an input signal input to the conversion input parts,
- the terminals of the groups including C conversion terminals (C is an integer equal to or larger than 2 (two)) that are electrically coupled to the conversion input parts, each of the conversion terminals being electrically coupled to one of the conversion input parts;
- each of the groups including the conversion terminals in the number of C/A at the same positions of the basic terminal arrangement, and
- the plurality of semiconductor chips being disposed so that the point of each of the semiconductor chips coincides with each other and the terminals of the groups of top-to-bottom overlap each other, the terminals, which overlap, being electrically coupled to each other.

44. (Original) A semiconductor device, comprising:

a plurality of stacked semiconductor chips having substantially the same structure each of the semiconductor chips including a semiconductor substrate, terminals of A groups (A is an integer equal to or larger than 2 (two)) formed on the semiconductor substrate, each of the groups including a plurality of terminals and an integrated circuit formed on the semiconductor substrate;

the plurality of terminals in each of the groups being arranged in accordance with predetermined basic terminal arrangement, each of the groups being disposed at each of positions that are defined by rotating one of the positions around a point, the integrated circuit including an element array that has a plurality of elements having the same function, and E element-array input parts (E is an integer equal to or larger than 2 (two)) for each being electrically coupled to any of the elements;

the terminals of the groups including F element-array terminals (F is an integer equal to or larger than 2 (two)) that are electrically coupled to the element-array input parts, each of the groups including the element-array terminals in the number of F/A at the same positions of the basic terminal arrangement; and

the plurality of semiconductor chips being disposed so that the point of each of the semiconductor chips coincides with each other and the terminals of the groups of top-to-bottom overlap each other, the terminals, which overlap, being electrically coupled to each other.

45-52. (Cancelled)